

CARRIER AND POLISHING APPARATUS

ABSTRACT OF THE DISCLOSURE

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A carrier and polishing apparatus enabling high precision polishing of a workpiece and enabling prevention of leak contamination and damage to the workpiece. A carrier 1 is provided with a carrier body 2, a pressure chamber 3, and a fluid passage portion 4 and a plurality of valve portions 5 are specially provided in the pressure chamber 3. Due to this, when the inside of the pressure chamber 3 becomes a negative pressure state, the valve portions 5 open and the wafer W is picked up by suction, while when it becomes a positive pressure state, the valve portions 5 close and the air in the pressure chamber 3 uniformly presses against the wafer W. Further, since the valve portions 5 close in the positive pressure state, the air in the pressure chamber 3 will not flow to the outside.

Figure 3